



LCP1521S/LCP152DEE

ASD (Application Specific Devices)

Programmable transient voltage suppressor for SLIC protection

Features

- Dual programmable transient suppressor
- Wide negative firing voltage range:
 $V_{MGL} = -150 \text{ V max.}$
- Low dynamic switching voltages:
 V_{FP} and V_{DGL}
- Low gate triggering current: $I_{GT} = 5 \text{ mA max}$
- Peak pulse current: $I_{PP} = 30 \text{ A (10/1000 } \mu\text{s)}$
- Holding current: $I_H = 150 \text{ mA min}$
- Low space consuming package

Description

These devices have been especially designed to protect new high voltage, as well as classical SLICs, against transient overvoltages.

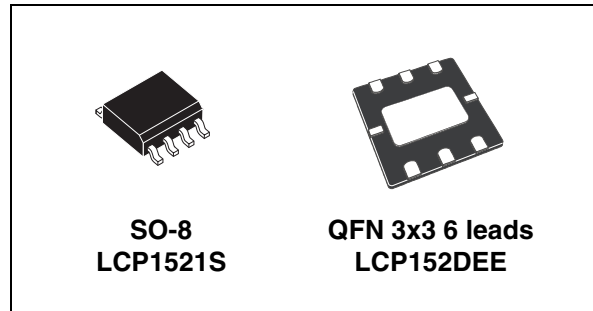
Positive overvoltages are clamped by 2 diodes. Negative surges are suppressed by 2 thyristors, their breakdown voltage being referenced to $-V_{BAT}$ through the gate.

These components present a very low gate triggering current (I_{GT}) in order to reduce the current consumption on printed circuit board during the firing phase.

Benefits

TRISILs™ are not subject to ageing and provide a fail safe mode in short circuit for a better level of protection. Trisils are used to ensure equipment meets various standards such as UL60950, IEC950 / CSA C22.2, UL1459 and FCC part 68. Trisils have UL94 V0 approved resin (Trisils are UL497B approved [file: E136224]).

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Order codes

| Part Number | Marking |
|-------------|---------|
| LCP1521S | CP152S |
| LCP1521SRL | CP152S |
| LCP152DEERL | LCP152 |

Figure 1. LCP1521S Functional diagram

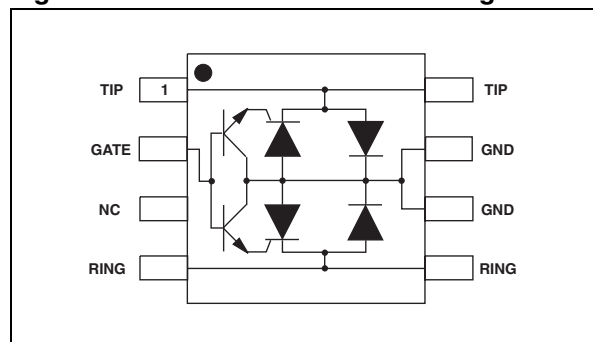
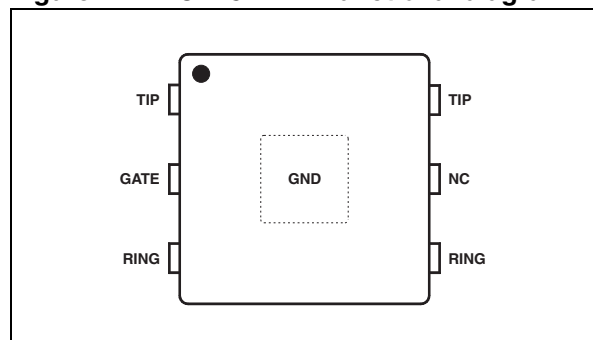


Figure 2. LCP152DEE Functional diagram



1 Characteristics

Table 1. Standards compliance

| Standard | Peak surge voltage (V) | Voltage waveform | Required peak current (A) | Current waveform | Minimum serial resistor to meet standard (Ω) |
|--|------------------------|----------------------------------|--|----------------------------------|---|
| GR-1089 Core First level | 2500 1000 | 2/10 μ s 10/1000 μ s | 500 100 | 2/10 μ s 10/1000 μ s | 12 24 |
| GR-1089 Core Second level | 5000 | 2/10 μ s | 500 | 2/10 μ s | 24 |
| GR-1089 Core Intra-building | 1500 | 2/10 μ s | 100 | 2/10 μ s | 0 |
| ITU-T-K20/K21 | 6000 1500 | 10/700 μ s | 150 37.5 | 5/310 μ s | 110 0 |
| ITU-T-K20 (IEC 61000-4-2) | 8000 15000 | 1/60 ns | ESD contact discharge ESD air discharge | | 0 0 |
| VDE0433 | 4000 2000 | 10/700 μ s | 100 50 | 5/310 μ s | 60 10 |
| VDE0878 | 4000 2000 | 1.2/50 μ s | 100 50 | 1/20 μ s | 0 0 |
| IEC61000-4-5 | 4000 4000 | 10/700 μ s 1.2/50 μ s | 100 100 | 5/310 μ s 8/20 μ s | 60 0 |
| FCC Part 68, lightning surge type A | 1500 800 | 10/160 μ s 10/560 μ s | 200 100 | 10/160 μ s 10/560 μ s | 22.5 15 |
| FCC Part 68, lightning surge type B | 1000 | 9/720 μ s | 25 | 5/320 μ s | 0 |

Table 2. Thermal resistances

| Symbol | Parameter | | Value | Unit |
|---------------|---------------------|------|-------|----------------|
| $R_{th(j-a)}$ | Junction to ambient | SO-8 | 120 | $^{\circ}$ C/W |
| | | QFN | 140 | |

Table 3. Electrical characteristics ($T_{amb} = 25^{\circ}C$)

| Symbol | Parameter | |
|-----------|---------------------------------------|--|
| I_{GT} | Gate triggering current | |
| I_H | Holding current | |
| I_{RM} | Reverse leakage current LINE / GND | |
| I_{RG} | Reverse leakage current GATE / LINE | |
| V_{RM} | Reverse voltage LINE / GND | |
| V_{GT} | Gate triggering voltage | |
| V_F | Forward drop voltage LINE / GND | |
| V_{FP} | Peak forward voltage LINE / GND | |
| V_{DGL} | Dynamic switching voltage GATE / LINE | |
| V_{RG} | Reverse voltage GATE / LINE | |
| C | Capacitance LINE / GND | |

Table 4. Absolute ratings ($T_{amb} = 25^{\circ}C$, unless otherwise specified)

| Symbol | Parameter | | Value | Unit |
|------------------|--|------------------------|-------------|------|
| I _{PP} | Peak pulse current | 10/1000 μs | 30 | A |
| | | 8/20 μs | 100 | |
| | | 10/560 μs | 35 | |
| | | 5/310 μs | 40 | |
| | | 10/160 μs | 50 | |
| | | 1/20 μs | 100 | |
| | | 2/10 μs | 150 | |
| I _{TSM} | Non repetitive surge peak on-state current (50Hz sinusoidal) | t = 20 ms | 18 | A |
| | | t = 200 ms | 10 | |
| | | t = 1 s | 7 | |
| I _{GSM} | Maximum gate current (50Hz sinusoidal) | t = 10 ms | 2 | A |
| V _{MLG} | Maximum voltage LINE/GND | -40° C < Tamb < +85° C | -150 | V |
| V _{MGL} | Maximum voltage GATE/LINE | -40° C < Tamb < +85° C | -150 | |
| T _{stg} | Storage temperature range | | -55 to +150 | ° C |
| T _j | Maximum junction temperature | | 150 | |
| T _L | Maximum lead temperature for soldering during 10 s. | | 260 | ° C |

Table 5. Repetitive peak pulse current


| Symbol | Definition | Example |  |
|--------|----------------------------|---|--|
| t_r | Rise time (μs) | Pulse waveform 10/1000 μs : $t_r = 10 \mu s$ $t_p = 1000 \mu s$ | |
| t_p | Pulse duration (μs) | | |

Table 6. Parameters related to the diode LINE / GND ($T_{amb} = 25^{\circ}C$)

| Symbol | Test conditions | | | Max | Unit |
|----------------|-----------------|--------|-------------------|-----|------|
| V_F | $I_F = 5A$ | | $t = 500 \mu s$ | 3 | V |
| $V_{FP}^{(1)}$ | 10/700 μs | 1.5 kV | $R_S = 10 \Omega$ | 5 | V |
| | 1.2/50 μs | 1.5 kV | $R_S = 10 \Omega$ | 9 | |
| | 2/10 μs | 2.5 kV | $R_S = 62 \Omega$ | 30 | |

1. See test circuit for V_{FP} (Figure 4.): R_S is the protection resistor located on the line card.

Table 7. Parameters related to the protection Thyristors ($T_{amb} = 25^{\circ}C$, unless otherwise specified)

| Symbol | Test conditions | | | Typ | Max | Unit |
|-----------|--------------------------|--------|-----------------------------------|-----|-----|---------|
| I_{GT} | $V_{GND} / LINE = -48 V$ | | | 0.1 | 5 | mA |
| I_H | $V_{GATE} = -48 V^{(1)}$ | | | 150 | | mA |
| V_{GT} | at I_{GT} | | | | 2.5 | V |
| I_{RG} | $V_{RG} = -150 V$ | | $T_j = 25^{\circ}C$ | | 5 | μA |
| | $V_{RG} = -150 V$ | | $T_j = 85^{\circ}C$ | | 50 | |
| V_{DGL} | $V_{GATE} = -48 V^{(2)}$ | | | | | V |
| | 10/700 μs | 1.5 kV | $R_S = 10 \Omega$ $I_{PP} = 30 A$ | | 7 | |
| | 1.2/50 μs | 1.5 kV | $R_S = 10 \Omega$ $I_{PP} = 30 A$ | | 10 | |
| | 2/10 μs | 2.5 kV | $R_S = 62 \Omega$ $I_{PP} = 38 A$ | | 25 | |

1. see functional holding current (I_H) test circuit

2. see test circuit for V_{DG} The oscillations with a time duration lower than 50ns are not taken into account.

Table 8. Parameters related to diode and protection Thyristors ($T_{amb} = 25^{\circ}C$, unless otherwise specified)

| Symbol | Test conditions | | | Typ | Max | Unit |
|----------|--|-------------------|---------------------|-----|-----|---------|
| I_{RM} | $V_{GATE} / LINE = -1 V$ | $V_{RM} = -150 V$ | $T_j = 25^{\circ}C$ | | 5 | μA |
| | $V_{GATE} / LINE = -1 V$ | $V_{RM} = -150 V$ | $T_j = 85^{\circ}C$ | | 50 | |
| C | $V_R = 50 V$ bias, $V_{RMS} = 1 V$, $F = 1 MHz$ | | | 15 | | pF |
| | $V_R = 2 V$ bias, $V_{RMS} = 1 V$, $F = 1 MHz$ | | | 35 | | |

Figure 3. Functional Holding Current (I_H) test circuit: GO-NO GO test

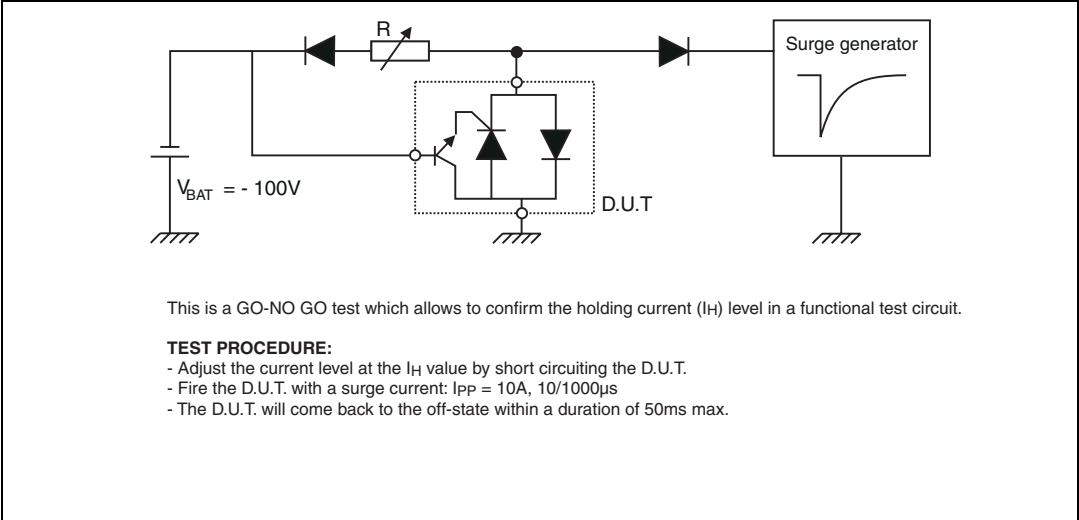
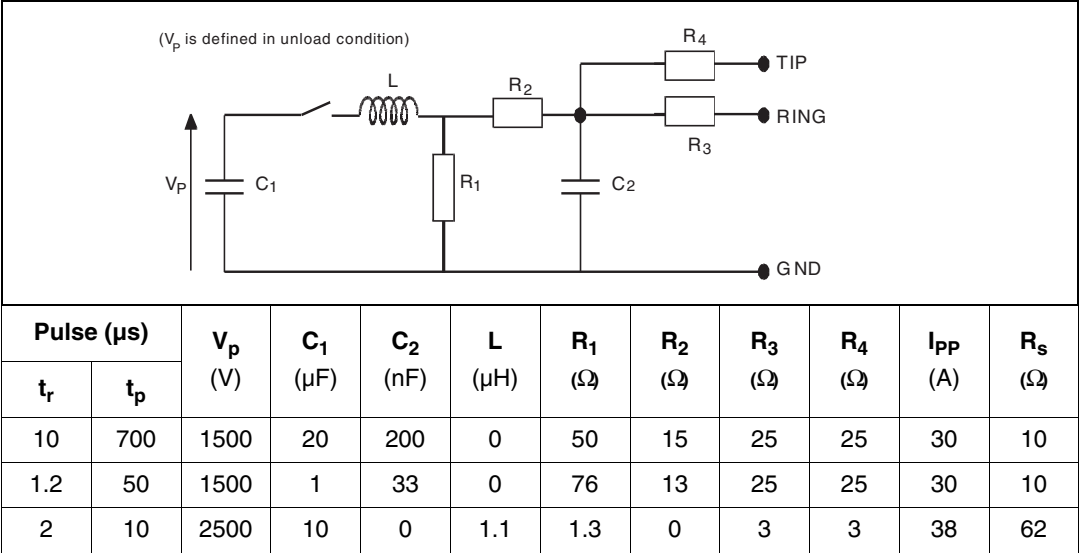


Figure 4. Test circuit for V_{FP} and V_{DGL} parameters



2 Technical information

Figure 5. LCP152 concept behavior

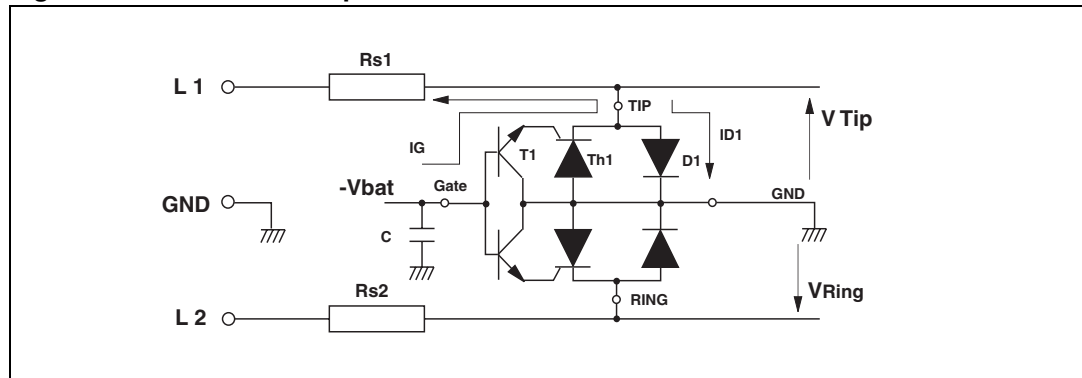


Figure 5. shows the classical protection circuit using the LCP152 crowbar concept. This topology has been developed to protect the new high voltage SLICs. It allows to program the negative firing threshold while the positive clamping value is fixed at GND.

When a negative surge occurs on one wire (L1 for example) a current I_G flows through the base of the transistor T1 and then injects a current in the gate of the thyristor Th1. Th1 fires and all the surge current flows through the ground. After the surge when the current flowing through Th1 becomes less negative than the holding current I_H , then Th1 switches off.

When a positive surge occurs on one wire (L1 for example) the diode D1 conducts and the surge current flows through the ground.

Figure 6. Example of PCB layout based on LCP152S protection

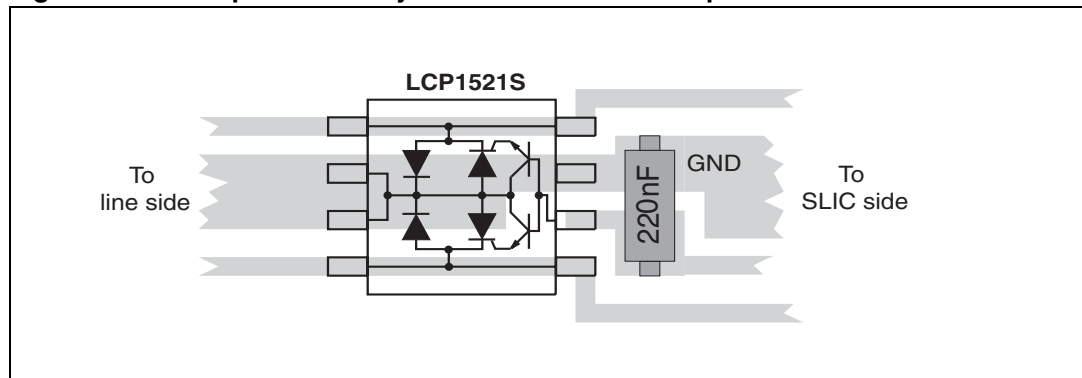


Figure 6. shows the classical PCB layout used to optimize line protection.

The capacitor C is used to speed up the crowbar structure firing during the fast surge edges.

This allows to minimize the dynamical breakover voltage at the SLIC Tip and Ring inputs during fast strikes. Note that this capacitor is generally present around the SLIC - Vbat pin.

So to be efficient it has to be as close as possible from the LCP152 Gate pin and from the reference ground track (or plan) (see *Figure 6.*). The optimized value for C is 220 nF.

The series resistors Rs1 and Rs2 designed in *Figure 5.* represent the fuse resistors or the PTC which are mandatory to withstand the power contact or the power induction tests

imposed by the various country standards. Taking into account this fact the actual lightning surge current flowing through the LCP is equal to:

$$I_{\text{surge}} = V_{\text{surge}} / (R_g + R_s)$$

With:

V_{surge} = peak surge voltage imposed by the standard.

R_g = series resistor of the surge generator

R_s = series resistor of the line card (e.g. PTC)

e.g. For a line card with 30 Ω of series resistors which has to be qualified under GR1089 Core 1000V 10/1000 μ s surge, the actual current through the LCP152 is equal to:

$$I_{\text{surge}} = 1000 / (10 + 30) = \underline{\underline{25 \text{ A}}}$$

The LCP152 is particularly optimized for the new telecom applications such as the fiber in the loop, the WLL, the remote central office. In this case, the operating voltages are smaller than in the classical system. This makes the high voltage SLICs particularly suitable.

The schematics of [Figure 7](#). give the most frequent topology used for these applications.

Figure 7. Protection of high voltage SLIC

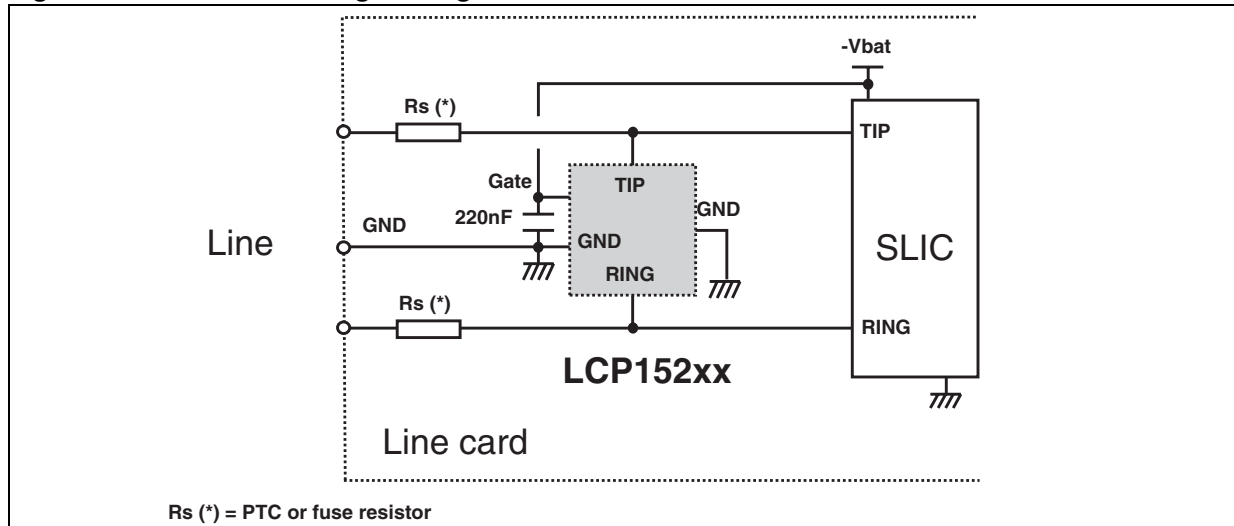
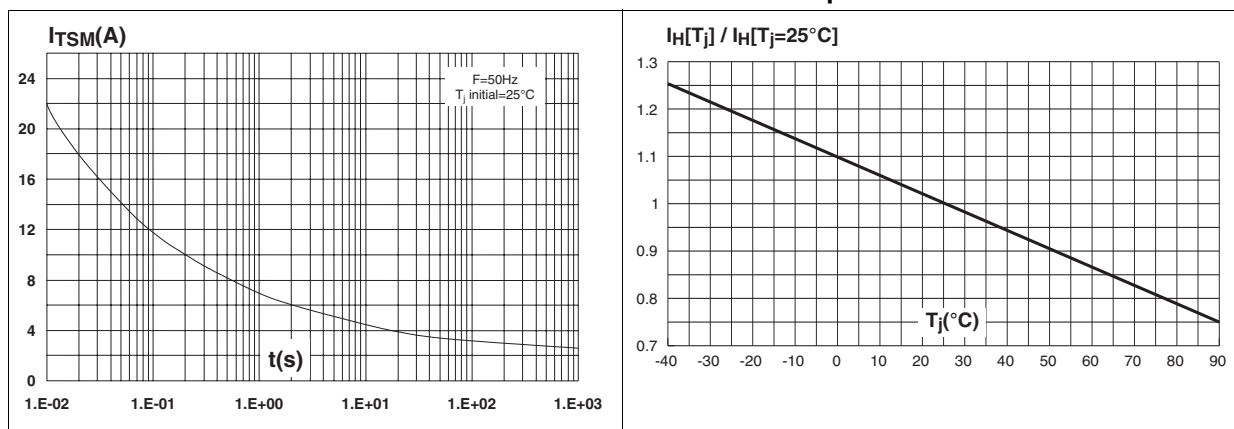


Figure 8. Surge peak current versus overload duration **Figure 9. Relative variation of holding current versus junction temperature**



3 Package information

Table 9. SO-8 Dimensions

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | | | 1.75 | | | 0.069 |
| A1 | 0.1 | | 0.25 | 0.004 | | 0.010 |
| A2 | 1.25 | | | 0.049 | | |
| b | 0.28 | | 0.48 | 0.011 | | 0.019 |
| C | 0.17 | | 0.23 | 0.007 | | 0.009 |
| D | 4.80 | 4.90 | 5.00 | 0.189 | 0.193 | 0.197 |
| E | 5.80 | 6.00 | 6.20 | 0.228 | 0.236 | 0.244 |
| E1 | 3.80 | 3.90 | 4.00 | 0.150 | 0.154 | 0.157 |
| e | | 1.27 | | | 0.050 | |
| h | 0.25 | | 0.50 | 0.010 | | 0.020 |
| L | 0.40 | | 1.27 | 0.016 | | 0.050 |
| L1 | | 1.04 | | | 0.041 | |
| k° | 0 | | 8 | 0 | | 8 |
| ccc | | | 0.10 | | | 0.004 |

Figure 10. Footprint (dimensions in mm)

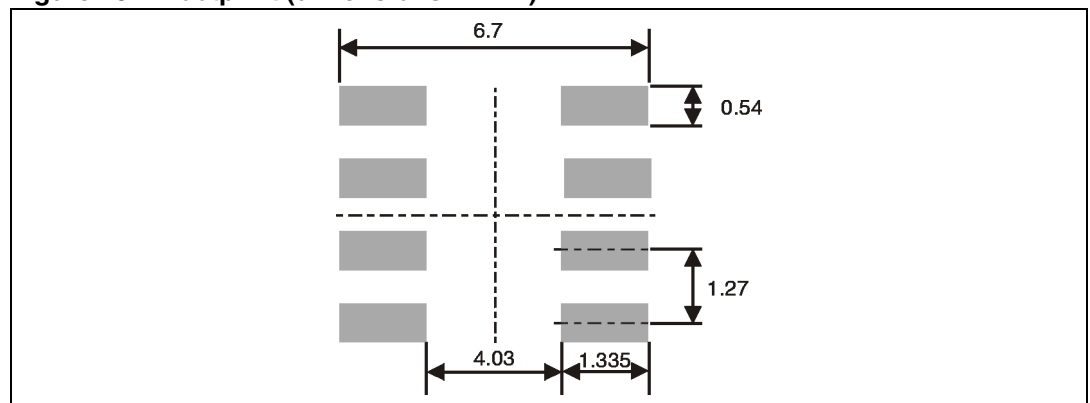
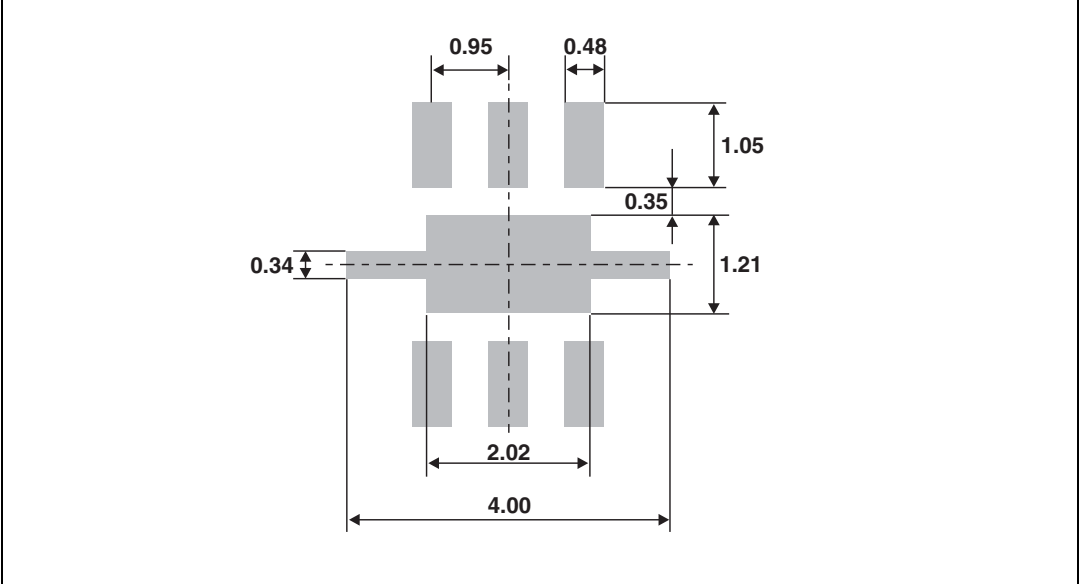


Table 10. QFN 3x3 6 Leads Package dimensions

| REF. | DIMENSIONS | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 0.80 | | 1 | 0.031 | | 0.040 |
| A1 | 0 | | 0.05 | 0 | | 0.002 |
| A2 | 0.65 | | 0.75 | 0.026 | | 0.030 |
| A3 | | 20 | | | 0.787 | |
| b | 0.33 | | 0.43 | 0.013 | | 0.017 |
| D | 2.90 | 3 | 3.10 | 0.114 | 0.118 | 0.122 |
| D2 | 1.92 | | 2.12 | 0.076 | | 0.083 |
| E | 2.90 | 3 | 3.10 | 0.114 | 0.118 | 0.122 |
| E2 | 1.11 | | 1.31 | 0.044 | | 0.051 |
| e | | 0.95 | | | 0.037 | |
| L | 0.20 | | 0.45 | 0.008 | | 0.018 |
| L1 | | 0.24 | | | 0.009 | |
| L2 | | | 0.13 | | | 0.005 |
| K | 0.20 | | | 0.008 | | |
| < | 0° | | 12° | 0° | | 12° |

Figure 11. QFN 3x3 6 Leads Footprint dimensions (in mm)



4 Ordering information

| Part Number | Marking | Package | Weight | Base qty | Delivery mode |
|----------------------------|---------|------------|---------|----------|---------------|
| LCP1521S | CP152S | SO-8 | 0.11 g | 100 | Tube |
| LCP1521SRL ⁽¹⁾ | CP152S | | | 2500 | Tape and reel |
| LCP152DEERL ⁽¹⁾ | LCP152 | QFN 3x3 6L | 0.022 g | 3000 | Tape and reel |

1. Preferred device

5 Revision history

| Date | Revision | Description of Changes |
|-------------|----------|--|
| Sep-2003 | 1A | First issue. |
| 08-Dec-2004 | 2 | 1/ Page 2 table 3: Thermal resistances changed from 130° C/W (SO-8) to 120° C/W and from 170° C/W (QFN) to 140° C/W. 2/ SO-8 and QFN footprint dimensions added. |
| 17-Feb-2005 | 3 | Table 9 on page 4: correction of typo on capacitance unit. |
| 03-May-2005 | 4 | Table 5 on page 3: I_{TSM} value @ $t = 1$ s from 4 A to 4.5 A. |
| 07-Jul-2006 | 5 | Replaced QFN package illustration on page 1. Reformatted document to current layout standard. Values of I_{TSM} modified in Table 4. SO-8 package dimensions updated in Table 9. |

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